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Suzanne Horcile



PATENT

Attorney Docket No.: DB000624-002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Mark S. Johnson, et al.)
Serial No.:	Not Yet Assigned))
Filed:	31 August 2000))

Entitled:

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Assistant Commissioner for Patents Washington, D.C. 20231

Dear Sir:

Pursuant to the provisions of 37 C.F.R. Sections 1.56, 1.97 and 1.98, Applicants submit the documents listed on the attached PTO Forms PTO/SB/08A PTO/SB/08B for consideration during prosecution of the above-captioned patent application filed herewith.

This statement is made solely for the purpose of compliance with the above-identified rules and is not intended to be a substitute for an independent search by the Examiner and no representation of any such nature is made or intended by this statement.

Also enclosed is a return postcard. Please date stamp and mail the postcard to acknowledge receipt of the above-mentioned correspondence.

Respectfully submitted,

Edward L. Pencoske Reg. No. 29,688

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Dated: 31 August 2000

Attorneys for Applicant

	Substitute for form 1449B/PTO
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Examiner Name	Pe. t	No
Attorney Docket Number	DB000624-002	, j

		OTHER PRIOR ART NON PATENT LITERATURE DOCUMENTS	
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SI	(JOHN H. LAU, Chip on Board Technologies for Multichie Modules;	
-	\ \ \	1994 pp. 2, 3, 24-27, 30-33, 330-337, Van Nostrand Reinhold,	
P	1	an International Thomson Publishing Company	
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	5	JOHN H. LAU ET AL., "Design, Materials, Processes, Reliability, and Applications," Chip Scale Package (CSP), McGraw-Hill (U.S.A. et al.),	
50	5	pp. vii - xvi, 1-2, 43, 61, 71, 87, 97, 107, 129, 143, 157, 173, 183,	
		201, 219, 233, 259, 283, 293,305, 313, 337, 349, 359, 377, 399,	
		407, 429, 439, 455, 467, 477, 487, 495, 519, 529, 545	

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